Materials Declaration Form

IPC	**1752**	**Version**	**2**
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	**Subsectionals ***	A-D **** : Required Field***

Supplier Information			
Company Name *	STMicroelectronics	**Response Date ***	2015-03-11
Contact Name *	Refer to Supplier comment section	**Contact Title**	Refer to Supplier comment section
Contact Phone *	Refer to Supplier comment section	**Contact Email ***	Refer to Supplier comment section
Authorized Representative *	Gabriella Garatti	**Representative Title**	DMA Material Declaration Champion
Representative Phone *	Refer to " Supplier Comment" section	**Representative Email ***	Refer to " Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement

Supplier Acceptance *	true	**Legal Declaration ***	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.

Signature Not
Verified

Digitally signed by
gabriella garatti
Date: 2015.04.09
09:13:26 +02:00

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
LINLD9A1-DSDLF	ZLW6*W416AB1	A	997C	2015-03-11
	Amount	**UoM**	**Unit type**	**ST ECOPACK Grade**
	0.6	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant			

Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		
NAC	NAC	NAC		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
NAC	NAC	NAC	CD00379442	

Package Designator	**Size**	**Nbr of instances**	**Shape**	
BARE DIE	0.74X1.34	10	flat	
Comment	A0W6 SAWN BUMPED WAFER 8 ON PLASTIC			

QueryList : ROHS directive 2011/65/EU _ANNEX IV

Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true

QueryList : REACH-17th December 2014

Query	Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	true

Material Composition Declaration						**Mfr Item Name**	**ZLW6*W416AB1**					
Homogeneous Material	**Material Group**	Mass	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die or Dies or Wafer (choose)	Other inorganic materials	0.575	mg	supplier	die	Silicon (Si)	7440-21-3		0.462	mg	803477	766170
				supplier	metallisation	Aluminium (Al)	7429-90-5		0.002	mg	3478	3317
				supplier	metallisation	Copper (Cu)	7440-50-8		0.035	mg	60870	58043
				supplier	metallisation	Tantalum (Ta)	7440-25-7		0.002	mg	3478	3317
				supplier	passivation	Silicon Nitride (SiN)	12033-89-5		0.004	mg	6957	6633
				supplier	passivation	Silicon Oxide	7631-86-9		0.035	mg	60870	58043
				supplier	passivation	Glass: Silicon Dioxide	7631-86-9		0.035	mg	60870	58043
BUMP	Precious metals	0.028	mg	supplier	bumps	Tin (Sn)	7440-31-5		0.027	mg	964286	44776
				supplier	bumps	Silver (Ag)	7440-22-4		0.001	mg	35714	1658
UBM	Precious metals	0.001	mg	supplier	UBM	Aluminium (Al)	7429-90-5		0.0001	mg	166666	166
				supplier	UBM	Copper (Cu)	7440-50-8		0.0004	mg	666667	663